



Material Content Data Sheet



Sales Product Name	TLE8444SL			Issued	4. July 2019			
MA#	MA005344656							
Package	PG-SSOP-24-7			Weight*	147.42 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.653	4.51	4.51	45130	45130
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		422	
	non noble metal	iron	7439-89-6	1.245	0.84		8448	
wire	non noble metal	copper	7440-50-8	50.568	34.30	35.19	343024	352000
	noble metal	gold	7440-57-5	0.720	0.49	0.49	4882	4882
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1137
encapsulation	plastics	epoxy resin	-	7.713	5.23		52324	
	inorganic material	silicondioxide	60676-86-0	75.961	51.54	56.88	515274	568735
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11395	11395
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2478	2478
glue	plastics	acrylic resin	-	0.499	0.34		3384	
	noble metal	silver	7440-22-4	1.769	1.20	1.54	11996	15380
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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